

LNPTM THERMOCOMPTM COMPOUND JF006EXZ

JF-1006 EM

DESCRIPTION

LNP THERMOCOMP JF006EXZ compound is based on Polyethersulfone (PES) resin containing 30% glass fiber. Added features of this grade include: Easy Molding.

GENERAL INFORMATION	
Features	Good Processability, High stiffness/Strength, High temperature resistance, No PFAS intentionally added
Fillers	Glass Fiber
Polymer Types	Polyethersulfone (PESU)
Processing Techniques	Injection Molding

INDUSTRY	SUB INDUSTRY
Building and Construction	Building Component
Consumer	Sport/Leisure, Personal Accessory, Home Appliances, Commercial Appliance
Electrical and Electronics	Mobile Phone - Computer - Tablets
Industrial	Electrical. Defense

TYPICAL PROPERTY VALUES

Revision 20231109

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL (1)			
Tensile Stress, break	139	MPa	ASTM D638
Tensile Strain, break	2.6	%	ASTM D638
Flexural Stress	192	MPa	ASTM D790
Flexural Modulus	8910	MPa	ASTM D790
Tensile Stress, break	145	MPa	ISO 527
Tensile Strain, break	1.9	%	ISO 527
Flexural Stress	209	MPa	ISO 178
Flexural Modulus	9700	MPa	ISO 178
IMPACT (1)			
Izod Impact, unnotched, 23°C	550	J/m	ASTM D4812
Izod Impact, notched, 23°C	77	J/m	ASTM D256
Instrumented Dart Impact Energy @ peak, 23°C	6	J	ASTM D3763
Izod Impact, unnotched 80*10*4 +23°C	40	kJ/m²	ISO 180/1U
Izod Impact, notched 80*10*4 +23°C	8	kJ/m²	ISO 180/1A
THERMAL (1)			
HDT, 1.82 MPa, 3.2mm, unannealed	212	°C	ASTM D648
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	213	°C	ISO 75/Af
Relative Temp Index, Elec ⁽²⁾	190	°C	UL 746B
Relative Temp Index, Mech w/impact (2)	190	°C	UL 746B
Relative Temp Index, Mech w/o impact (2)	190	°C	UL 746B



PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
PHYSICAL (1)			
Density	1.6	g/cm³	ASTM D792
Moisture Absorption, (23°C/50% RH/24 hrs)	0.21	%	ASTM D570
Mold Shrinkage, flow, 24 hrs ⁽³⁾	0.3 – 0.5	%	ASTM D955
Mold Shrinkage, xflow, 24 hrs ⁽³⁾	0.6 – 0.8	%	ASTM D955
FLAME CHARACTERISTICS (2)			
UL Yellow Card Link	<u>E121562-101283894</u>	-	-
UL Recognized, 94V-0 Flame Class Rating	0.5	mm	UL 94
INJECTION MOLDING (4)			
Drying Temperature	120 – 150	°C	
Drying Time	4	Hrs	
Maximum Moisture Content	0.05	%	
Melt Temperature	355 – 370	°C	
Front - Zone 3 Temperature	370 – 380	°C	
Middle - Zone 2 Temperature	360 – 370	°C	
Rear - Zone 1 Temperature	345 – 355	°C	
Mold Temperature	140 – 150	°C	
Back Pressure	0.3 – 0.7	MPa	
Screw Speed	60 – 100	rpm	

- (1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.
- (2) UL Ratings shown on the technical datasheet might not cover the full range of thicknesses and colors. For details, please see the UL Yellow Card.
- (3) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.
- (4) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

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